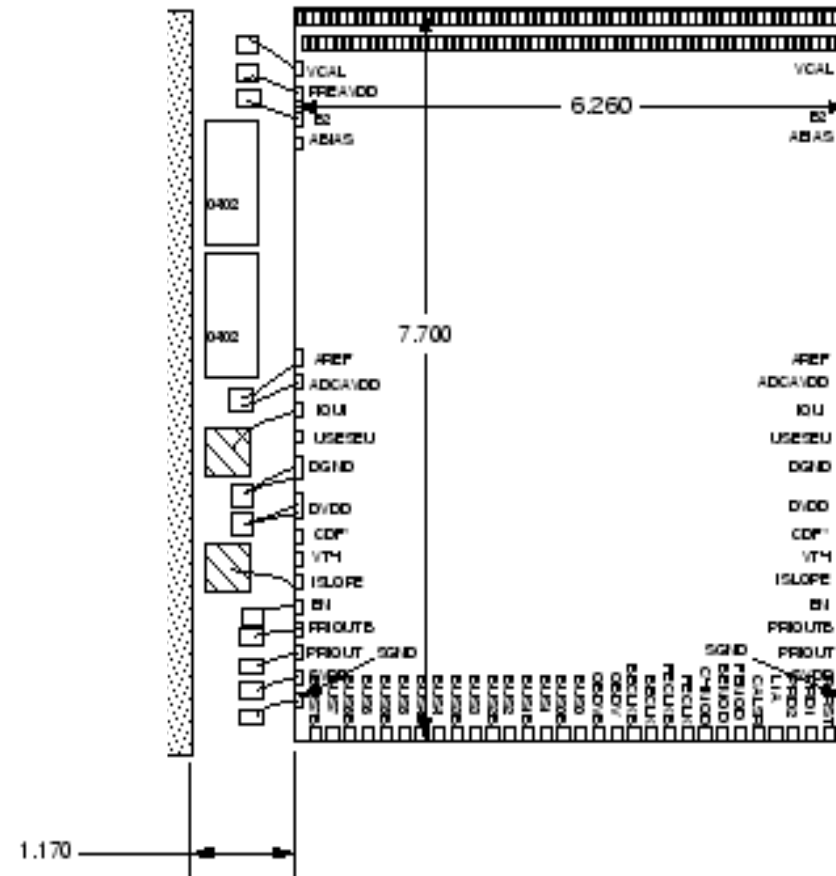


SVX4 Finger

- SVX4 has side bond pads
 - AVDD & DVDD, DGND
 - AVDD bypass capacitor
 - VCAL
 - One more capacitor necessary for preamp
 - Two resistors to set ADC parameters
 - Priority_IN and _OUT, Top/Bottom Neighbor
- Finger between chips allows for bonding
 - 0.5 mm alumina ceramic
 - One (or two) metal layer design
 - 4 surface mounted components
 - Can be simpler if on-chip bypassing works



SVX4 Finger

- Checked possibility to bond between chips
 - No finger needed, finger components are integrated on the hybrid
 - Distance between chips 1.37 mm
 - 0.3 mm height dislevel
 - No problems found
 - Ray H. is checking if acceptable for stuffing houses
- Propose to integrate finger with hybrids for L1-5
 - Need to change layouts for L1, L2-5 hybrid
 - 2 capacitors stay between chips, 2 resistors can be moved outside
 - Need to kludge fingers for L1 prototypes

